

Electronic Patent Application Fee Transmittal

Application Number:	10597514			
Filing Date:	27-Jul-2006			
Title of Invention:	Mold, Method of Forming the Same, and Method of Producing Polycrystalline Silicon Substrate Using the Mold			
First Named Inventor/Applicant Name:	Youhei Sakai			
Filer:	Lawrence James McClure/Diane Zynn			
Attorney Docket Number:	81872.0124			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810